



# 100% Material Declaration Data Sheet TQ176

PK170 (v1.2) October 5, 2006

Material Declaration Data Sheet

**Average Weight: 1.776259 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.02752</b>	<b>1.55%</b>
	Silicon	7440-21-3	100.00		0.02752	
<b>Die Attach Material</b>					<b>0.003709</b>	<b>0.21%</b>
	anhydride	Trade Secret	7.50		0.000278175	
	Silver	7440-22-4	77.50		0.002874475	
	Epoxy resin	Trade Secret	15.00		0.00055635	
<b>Mold Compound</b>					<b>1.465</b>	<b>82.48%</b>
	Epoxy Resin (EP)	Trade Secret	7.00		0.10255	
	Phenolic Resin	Trade Secret	5.00		0.07325	
	Carbon Black	1333-86-4	0.30		0.004395	
	Silica	60676-86-0	87.70		1.284805	
<b>Leadframe</b>					<b>0.2601</b>	<b>14.64%</b>
	Copper	7440-50-8	94.3		0.2452743	
	Magnesium	7439-95-4	0.30		0.0007803	
	Nickel	7440-02-0	1.2		0.0031212	
	Silicon	7440-21-3	4.2		0.0109242	
<b>Bond Wire</b>					<b>0.00393</b>	<b>0.22%</b>
	Gold	7440-57-5	100.00		0.00393	
<b>Ext. Plating</b>					<b>0.016</b>	<b>0.90%</b>
	Tin	7440-31-5	85.00		0.0136	
	Lead	7439-92-1	15.00		0.0024	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
10/5/06	1.2	Updated component descriptions.